

Microchip Technology Limited

March 2020

Product/Process Change Notification No: 2020-001

Change Classification: Major

Subject: Microchip DPG PDM Non Hermetic Product Supply Chain Update

Description of Change: This correspondence is official notification of the addition of second die source for the Microchip manufactured parts listed below. This is a follow on PCN from IPCN 2016-010. Product built with original die source and assembly will remain available until we deplete bridging inventory that we have in die bank. The part specifications are available on the Microsemi website at www.microsemi.com

Reason for Change: As part of Microchip's search for continued operational and service efficiencies, current non-hermetic product offering is being reviewed for run rates, revenue, margin and potential growth

Application Impact: There will be no change to form, fit or function of the product.

Method of Identifying Changed Product:

This will be listed on the Certificate of Conformance shipped with all affected products.

Die Source: China

Assembly Division: Philippines

Screening Division: Ireland

Products Affected by this Change: See below

All M/MA/MXL/MX level parts in the following Transient Voltage Suppressor series

MUPT5 thru MXUPT48, e3

MUPTB5 thru MXUPTB48, e3

MUPT8R thru MXUPT48R, e3

Production Shipment Schedule:

During a transition period, customers may see shipments with either location while any existing inventory of parts is depleted.

Qualification Plan:

Summary of Qualification Tests

Screening Level	Test Performed	Conditions	Duration or Qty	Standard / Ref	Sample size	No. Of Lots	Failures
M	HTRB	125 °C, Bias at Vrwm	1000 hours	MIL-STD-750F Method 1038	77	3	0
M	Autoclave	121 °C, 100 % RH, 15 psig	96 hours	JESD22-A102	77	3	0
M	Temperature Cycle	-55 °C to +150 °C	1000 cycles	JESD22-A104 Appendix 6	77	3	0
M	H3TRB	85 °C, 85% RH, 15psig	1000 hours	JESD22-A101	77	3	0
M	Resistance to Solder Heat	-	-	JESD22-B106	77	3	0
M	Solderability (incl. steam age)	-	-	J-STD-002	10	2	0
MX	Visual and Mechanical Review	-	-	MIL-STD-750 Method 2071	45	3	0
MX	Vc	10/1000 μ s 100 % IPP	1 repetition	MIL-STD-750 Method 4066	45	1	0
MX	Temperature Cycling	-55 °C to +150 °C	100 cycles	MIL-STD-750 Method 1051	22	2	0
MX	High Temperature (non-operating)	150 °C	340 hours	MIL-STD-750 Method 1032	32	2	0
MX	HTRB	125 °C	1000 hours	MIL-STD-750 Method 1038	45	3	0
MX	Salt Atmosphere (Corrosion)	-	-	MIL-STD-750 Method 1021	15	3	0

Samples Availability: Not applicable.

Contact Information:

If you have any questions concerning this change please contact your regional Microchip Sales person: <http://www.microsemi.com/sales-contacts/0>

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Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi/Microchip Sales Office, the factory contact shown above, or your local distributor.

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